

Chuck Cleaning Wafers

Unmatched Cleaning Performance

Entegris' Chuck Cleaning Wafers (CCW) boast a revolutionary cleaning mechanism that meticulously removes contaminants from the chuck surface. This results in improved yield, reduced test errors, and enhanced overall efficiency.

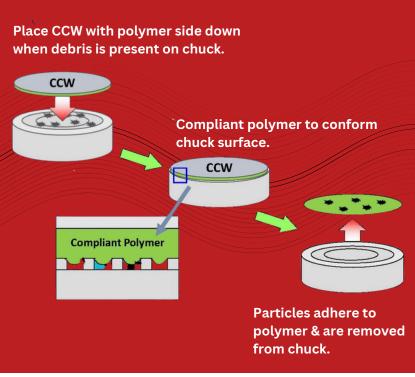
Compatibility and Flexibility

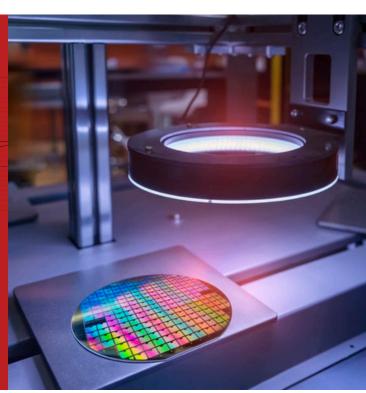
The Chuck Cleaning Wafers (CCW) are compatible with a wide range of equipment, making them a versatile choice for semiconductor manufacturers worldwide. CCWs are available for:

PVD: CCW solves the backside pressure fault problem caused by particles on the chuck. It also contributes to improvement of thin film uniformity. Fixes chucking errors in less than 5 minutes vs. 12 hour wet clean. CCW can be used >100 times with >75% success reducing Helium leak.

Etch: CCW solves Helium leak problem caused by particles on the chuck (customers have >75% success reducing Helium leak with CCW). Fixes chucking errors in less than 5 minutes vs. 8 hour wet clean. CCW can be used >100 times.

Lithography: CCW solves the problem of hot spot, which causes defocus defect. Prevents critical focus errors on high-throughput, extremely expensive tools. CCW can be used >100 times with >75% success fixing hot spots. ITS has developed new polymer chemistry that is better at picking up polymer without sticking to advanced lithography chucks. The new PM-PLUS part is very flat and can pick up very small particles.







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